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²¹ **Supporting Information**

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23 **Table S1:** Calculated and measured resistance of the fabricated microbolometers.

Bolometers	ρ_{Au} $(\Omega \cdot cm)^1$	Cal. Resistance (Ω)	Exp. Resistance (Ω)
bare Au-200		115	115
bare Au-500	3×10^{-6}	110	120
bare Au-800		135	146
$MIM-200$	top: 8×10^{-6}	102	104
MIM-500	bottom: 3×10^{-6}	98	104
MIM-800	(Parallel Connection)	120	134

24 **The calculated resistance** (R) is obtained by using $R = \rho \cdot l / s$, where ρ , *l*, *s* are 25 **the electrical resistivity, length, and cross-sectional area of the resistor,** 26 **respectively.**

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 Figure S1:Photographs and microscope images of the fabricated two types 32 microbolometers with various efficient areas, scale bars are 200µm.

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Figure S2: Experimental measured absorption spectra of the MIM microbolometers

- with three area size.
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 Figure S3: The experimentally measured the resistance change of the fabricated microbolometer (magenta dotted line) under 0.2 mA and corresponding calculated 51 ln(R/R₀) (blue dotted line). R₀ is the resistance of the device at temperature of 273 K, 52 and the fitted TCR is 0.0014 K^{-1} .

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 Figure S4: The experimentally measured responsivities of microbolometers with 58 efficient area size of 500×500 μ m², and 800×800 μ m², as a function of modulation frequency.

⁶¹ **Note 1**:**Calculation of the thermal conductance**

 62 The thermal conductance *G* can be theoretically calculated by²

63 $G = k \cdot S/h$ (S1)

64 Where k , S and h are the thermal conductivity of material, the contact area, and the 65 heat transfer distance, respectively.

 Firstly, 2D heat distributions were calculated based finite element methods. In the simulations, we replace the winding structure as planar thin films for both MIM and bare Au devices to simplify the calculation, the sizes and thicknesses for each film are as the real devices. The planar thin film structures serve as the heat source on a quartz substrate. The heat conductivities of gold, alumina, and quartz were taken from 71 literature². The thermal power density of the heat source of MIM structures is set one order of magnitude larger than that of the bare Au control samples. After getting heat distribution of each device at the response time, we then utilize the lateral heat transfer distance *d* and vertical heat transfer distance *t* obtained from the simulated results to calculate the contact area $(S=d^2)$ and distance $(h=t)$. Finally, the effective thermal conductance *G*, and the ratio of the absorption coefficient at 638 nm to the 77 effective thermal conductance (η/G) for each microbolometer can be calculated using Eq. (S1). The calculated results are listed in Table S2.

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80 **Table S2:** Calculated *G* and η/G of the fabricated microbolometers.

Bolometers	τ (ms)	$S(m^2)$	h(m)	G(W/K)	η/G
bare Au-200	4.29	2.03×10^{-7}	1.50×10^{-4}	1.86×10^{-3}	47.28
bare Au-500	6.60	5.63×10^{-7}	1.50×10^{-4}	5.18×10^{-3}	17.02
bare Au-800	6.90	1.21×10^{-6}	2.00×10^{-4}	8.35×10^{-3}	10.55
$MIM-200$	2.14	1.60×10^{-7}	1.20×10^{-4}	1.84×10^{-3}	413.19
MIM-500	4.50	5.93×10^{-7}	1.50×10^{-4}	5.45×10^{-3}	139.38
MIM-800	4.85	1.44×10^{-6}	1.50×10^{-4}	1.32×10^{-2}	57.39

SI references:

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- *of Heat and Mass Transfer*, New York: Wiley, 1996.